

The Pending Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Previously Presented) An electronics unit, comprising:

a low multi-point metallic mount comprising a material having a melting point below 600 degrees Celsius;

an insulating layer comprising a sintered electrically insulating polymer layer arranged on said mount;

a conductor track system comprising a sintered glass frit with a noble metal filling arranged on said insulating layer, the sintered glass frit having a melting point that is lower than the melting point of the metallic mount, so that the glass frit is sinterable onto said mount;

a resistance layer printed onto the polymer layer within one area of the conductor track system; and

electronic power components arranged on said conductor track system.
2. (Original) The electronics unit of claim 1, wherein said noble metal filling comprises one of a silver filling and a filling containing silver.
3. (Original) The electronics unit of claim 1, wherein said glass frit is a low melting-point glass frit.

4. (Original) The electronics unit of claim 2, wherein said glass frit is a low melting-point glass frit.

5. (Original) The electronics unit of claim 1, wherein said mount is made of a material from the group consisting of aluminum and an aluminum alloy.

6. (Original) The electronics unit of claim 1, wherein said mount comprises cooling ribs.

7. (Previously Presented) The electronics unit of claim 1, wherein said at least one power components comprise at least one of a power semiconductor element and a driver component.

8. (Previously Presented) The electronics unit of claim 1, further comprising at least one of an electrical and an electronic component arranged on the conductor track system.

9. (Previously Presented) The electronics unit of claim 8, wherein said power components and said at least one of an electrical and an electronic component are conductively connected to the conductor track system by one of soldering and bonding.

10. (Original) The electronics unit of claim 1, wherein said power components are conductively connected to the conductor track system by one of soldering and bonding.

11. (Original) The electronics unit of claim 1, wherein said electrically insulating polymer layer has a thickness of about $>20\text{ }\mu\text{m}$.

12. (Previously Presented) The electronics unit of claim 1, further comprising:
a further insulating layer comprising a sintered polymer arranged on said conductor track system and on one of said electronic power components;
a further conductor track system comprising a sintered glass frit with noble metal filling arranged on said further insulating layer; and
a further electronic power component arranged on said further conductor track system.

13.-24. (Canceled)